



TET ESTEL AS
ESTONIA

**June
2016**

**Series
T343-500**

Phase Control Press-Pack Thyristor Type T343-500

Center amplifying gate
Low on-state and switching losses
Designed for traction and industrial applications

Maximum mean on-state current	I_{TAV}	500 A
Maximum repetitive peak off-state and reverse voltage	U_{DRM}	2000 ÷ 2800 V
Turn-off time	t_q	200; 250; 320 µs
U _{DRM} , U _{RRM} , V	2000	2200
Voltage code	20	22
Tvj, °C	- 60 ÷ 125	

MAXIMUM ALLOWABLE RATINGS				
Symbols and parameters		Units	T343-500	Conditions
I _{TAV}	Mean on-state current	A	500 830	Tc=88 °C, Tc=55 °C, 180° half-sine wave, 50 Hz
I _{TRMS}	RMS on-state current	A	785	Tc=88 °C
I _{TSM}	Surge on-state current	kA	10 11	Tvj=125°C Tvj=25°C
I ² t	Limiting load integral	kA ² s	500 605	Tvj=125°C Tvj=25°C
U _{DRM} , U _{RRM}	Repetitive peak off-state and reverse voltage	V	2000÷2800	Tj min≤Tvj≤Tjm 180° half-sine wave, 50 Hz Gate open
U _{DSM} , U _{RSR}	Non-repetitive peak off-state and reverse voltage	V	2100÷2900	Tj min≤Tvj≤Tjm 180° half-sine wave tp=10 ms, Single pulse Gate open
(dit/dt) crit	Critical rate of rise of on-state current : non - repetitive repetitive	A/µs	400 200	Tvj=125°C ; UD=0,67 U _{DRM} , Gate pulse : 10V, 5 Ω, 1µs rise time, 10 µs
U _{RGm}	Peak reverse gate voltage	V	5	Tj min≤Tvj≤Tjm
T _{Stg}	Storage temperature	°C	-60÷80	
Tvj	Junction temperature	°C	-60÷125	

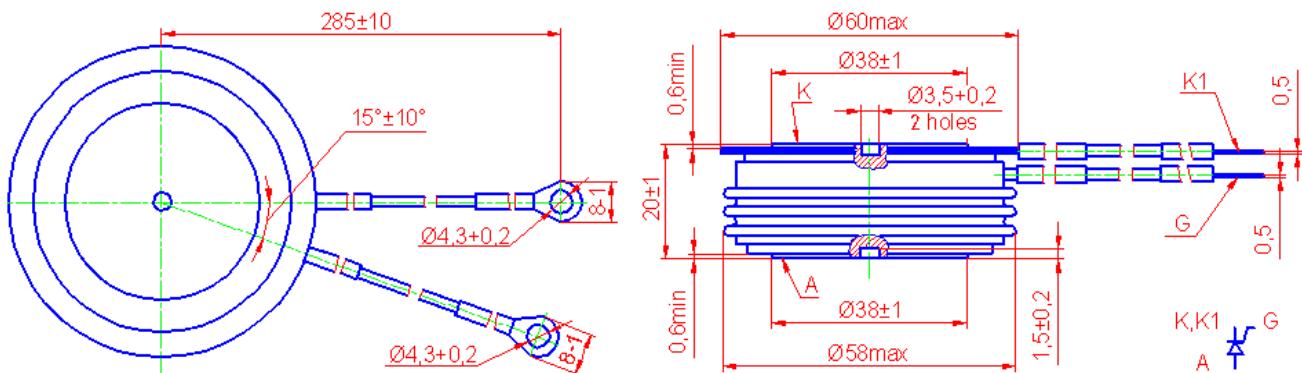
CHARACTERISTICS

U _{TM}	Peak on-state voltage	V	2,2	Tvj=25°C, I _{TM} =3,14 I _{TAV}
U _{T(TO)}	Threshold voltage	V	1,3	Tvj=125°C
R _T	On-state slope resistance	mΩ	0,65	1,57 I _{TAV} < I _T <4,71 I _{TAV}
I _{DRM} I _{RRM}	Repetitive peak off-state and reverse current	mA	50 50	Tvj=125°C, UD= U _{DRM} UR= U _{RRM}

CHARACTERISTICS					
Symbols and parameters		Units	T343-500	Conditions	
I _L	Latching current	A	1	T _{VJ} =25°C, U _D =12V Gate pulse : 10V, 5Ω, 1 μs rise time, 10μs	
I _H	Holding current	A	0,6	T _{VJ} =25°C, U _D =12V, Gate open	
U _{GT}	Gate trigger direct voltage	V	2,5 5,0	T _{VJ} =25°C, T _{VJ} =-60°C	U _D =12V
I _{GT}	Gate trigger direct current	A	0,3 0,85	T _{VJ} =25°C, T _{VJ} =-60°C	
U _{GD}	Gate non-trigger direct voltage	V	0,25	T _{VJ} =125°C, U _D = 0,67 U _{DRM} Direct gate current	
I _{GD}	Gate non-trigger direct current	mA	10		
t _{gd}	Delay time	μs	3,2	T _{VJ} =25°C, U _D =500V I _{TM} = 500 A Gate pulse : 10V, 5Ω, 1 μs rise time, 10μs	
t _{gt}	Turn-on time	μs	8		
t _q	Turn-off time	μs	200÷320	T _{VJ} =125°C, I _{TM} =500 A d _{iR} /dt =10 A/μs, U _R =100V U _D = 0,67 U _{DRM} d _{uD} /dt=50 V/μs	
Q _{rr}	Recovered charge	μC	1200	T _{VJ} =125°C, I _{TM} =500 A d _{iR} /dt =10 A/μs, U _R =100V	
t _{rr}	Reverse recovery time	μs	22		
I _{rrm}	Peak reverse recovery current	A	110	T _{VJ} =125°C, U _D = 0,67 U _{DRM} Gate open	
(d _{uD} /dt) _{crit}	Critical rate of rise of off-state voltage	V/μs	500 1000		
R _{thjc}	Thermal resistance junction to case	°C/W	0,032	Direct current, double side cooled	

ORDERING						
	T	343	500	28	7	2
	1	2	3	4	5	6

1. Phase control thyristor.
2. Design version.
3. Mean on-state current, A.
4. Voltage code (28=2800 V).
5. Critical rate of rise of off-state voltage ($6 \geq 500 \text{ V}/\mu\text{s}$, $7 \geq 1000 \text{ V}/\mu\text{s}$).
6. Group of turn-off time ($d\text{u}_D/\text{dt} = 50 \text{ V}/\mu\text{s}$, $K2 \leq 320\mu\text{s}$, $2 \leq 250 \mu\text{s}$, $P2 \leq 200 \mu\text{s}$).



Mounting force : 13÷19 kN
Weight : 260 grams